

MCP100/101

1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

V_{DD} 7.0V
 All inputs and outputs w.r.t. V_{SS} -0.6V to $V_{DD} + 1.0V$
 Storage temperature -65°C to +150°C
 Ambient temp. with power applied -65°C to +125°C
 ESD protection on all pins ≥ 2 kV

***Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC AND AC CHARACTERISTICS

All parameters apply at the specified temp and voltage ranges unless otherwise noted.		$V_{DD} = 1.0 - 5.5V$ Industrial (I): -40°C to +85°C				
Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Operating Voltage Range	V_{DD}	1.0	—	5.5	V	
V_{DD} Value to $\overline{RESET}/RESET$	V_{DDMIN}	1.0	—	—	V	
Operating Current	I_{DD}	—	45	60	μA	$V_{DD} = 5.5V$ (no load)
V_{DD} Trip Point	MCP10X-270	V_{TRIP}	2.55	2.625	2.7	V
	MCP10X-300		2.85	2.925	3.0	
	MCP10X-315		3.0	3.075	3.15	
	MCP10X-450		4.25	4.375	4.50	
	MCP10X-460		4.35	4.475	4.60	
	MCP10X-475		4.50	4.625	4.75	
RESET Low Level Output Voltage (MCP100)	MCP100-270	V_{OL}	—	—	0.4	V
	MCP100-300					
	MCP100-315					
	MCP100-450		—	—	0.6	
RESET Low Level Output Voltage (MCP101)	MCP101-270	V_{OL}	—	—	0.4	V
	MCP101-300					
	MCP101-315					
	MCP101-450		—	—	0.6	
RESET High Level Output Voltage (MCP100)	MCP100-XXX	V_{OH}	$V_{DD}-0.7$	—	—	V
	(All V_{TRIP} Points)					
RESET High Level Output Voltage (MCP101)	MCP101-XXX	V_{OH}	$V_{DD}-0.7$	—	—	V
	(All V_{TRIP} Points)					
Threshold Hysteresis	V_{HYS}	—	50	—	mV	
V_{DD} Detect to $\overline{RESET}/RESET$ Inactive	t_{RPU}	150	350	700	ms	
V_{DD} Detect to $\overline{RESET}/RESET$	t_{RPD}	—	10	—	μs	V_{DD} ramped from $V_{TRIPMAX} + 250$ mV down to $V_{TRIPMIN} - 250$ mV

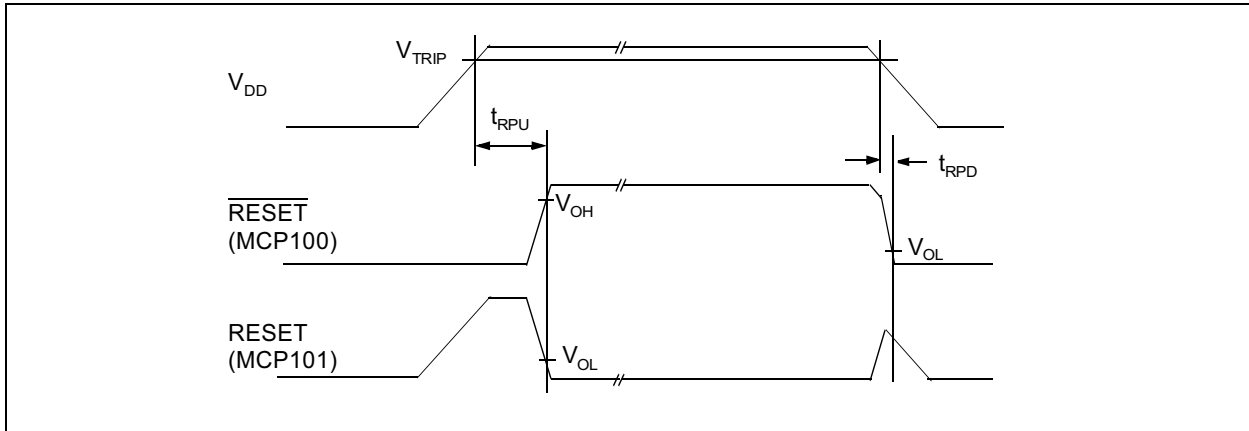


Figure 1-1: MCP100/101 Timing Diagram

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2.0 APPLICATIONS INFORMATION

2.1 The Need for Supervisory Circuits

For many of today's microcontroller applications, care must be taken to prevent low power conditions that can cause many different system problems. The most common causes are brown-out conditions where the system supply drops below the operating level momentarily, and the second, is when a slowly decaying power supply causes the microcontroller to begin executing instructions without enough voltage to sustain SRAM and producing indeterminate results.

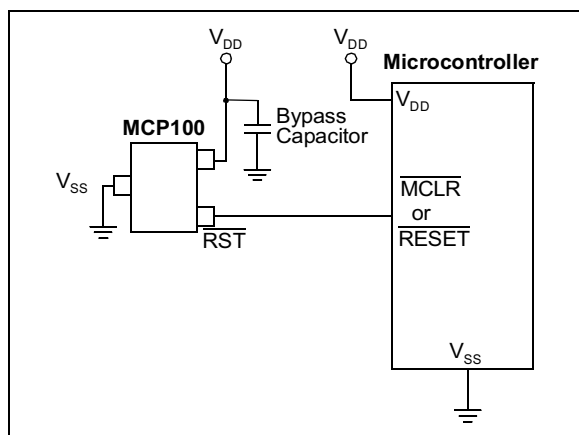


Figure 2-1: Typical Application

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

2.2 Negative Going V_{DD} Transients

Many system designers implementing POR circuits are concerned about the minimum pulse width required to cause a reset. Figure 2-2 shows typical transient duration vs. reset comparator overdrive for which the MCP100/101 will not generate a reset pulse. It shows that the farther below the trip point the transient pulse goes, the duration of the pulse required to cause a reset gets shorter. A 0.1 μF bypass cap mounted as close as possible to the V_{DD} pin provides additional transient immunity.

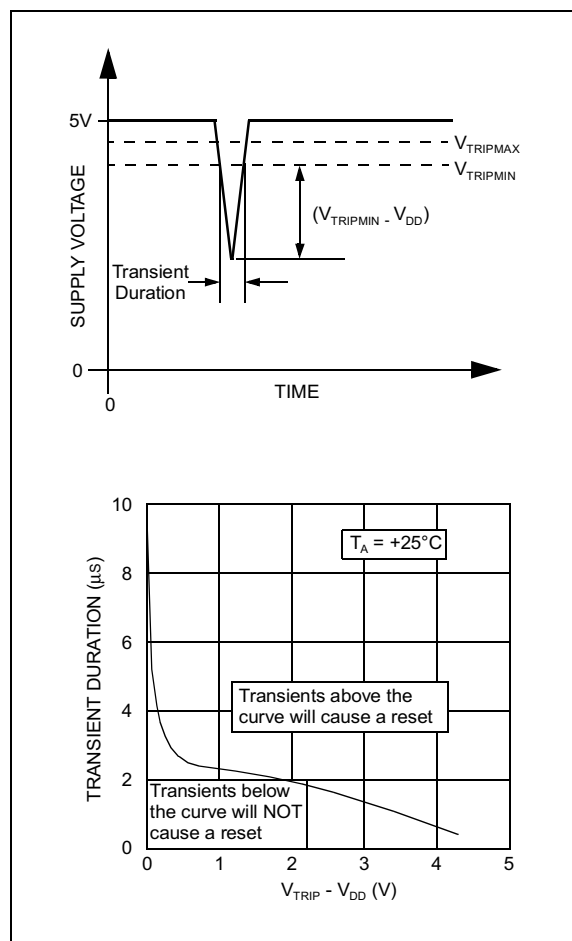


Figure 2-2: Typical Transient Response

2.3 Effect of Temperature on Timeout Period (t_{RPU})

The timeout period (t_{RPU}) determines how long the device remains in the reset condition. This is controlled by an internal RC timer and is effected by both V_{DD} and temperature. The graph shown in Figure 2-3 shows typical response for different V_{DD} values and temperatures.

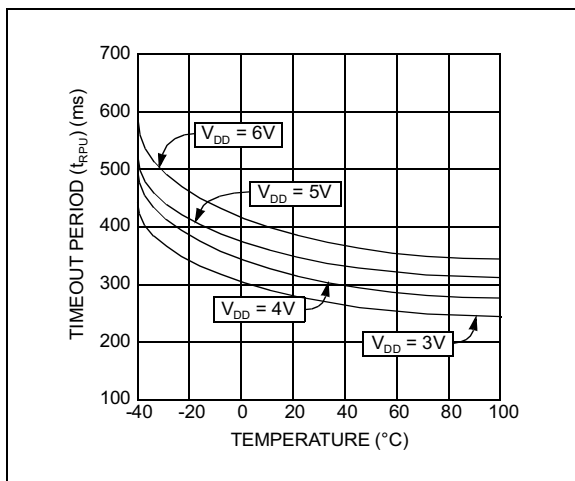


Figure 2-3: Typical t_{RPU} vs. Temperature

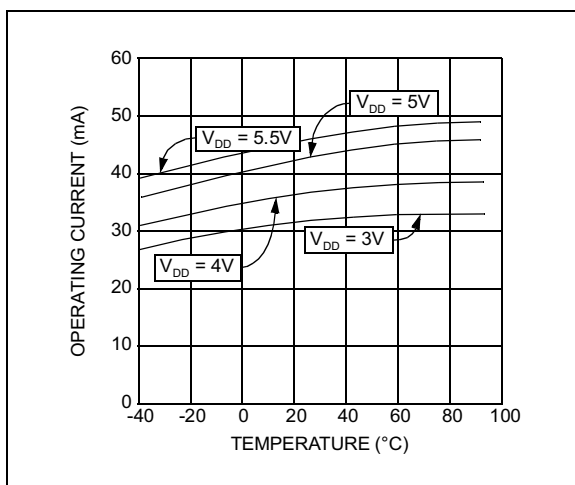


Figure 2-4: I_{DD} vs. Temperature

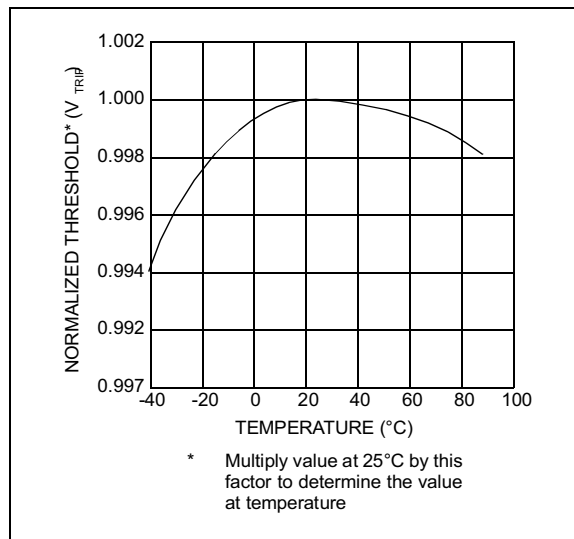


Figure 2-5: Normalized V_{TRIP} vs. Temperature

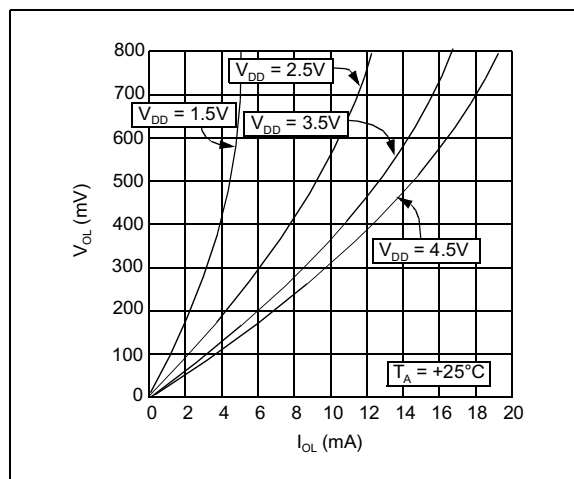
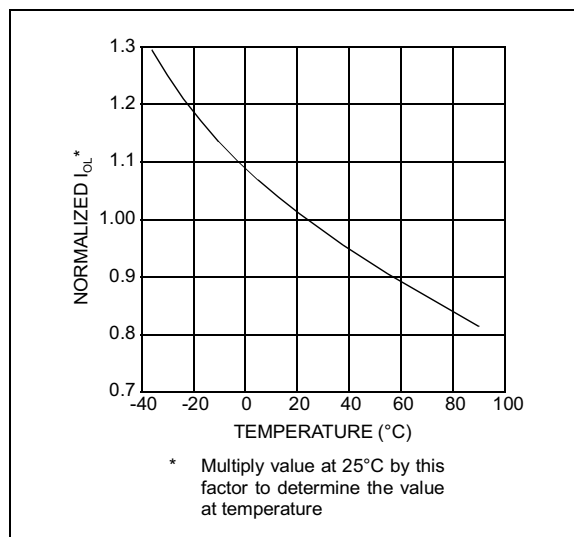


Figure 2-6: V_{OL} vs. I_{OL}



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Figure 2-7: Normalized I_{OL} vs. Temperature

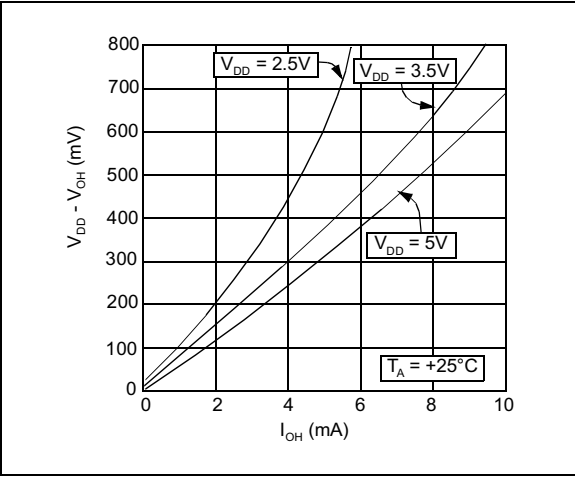


Figure 2-8: $V_{DD} - V_{OH}$ vs. I_{OH}

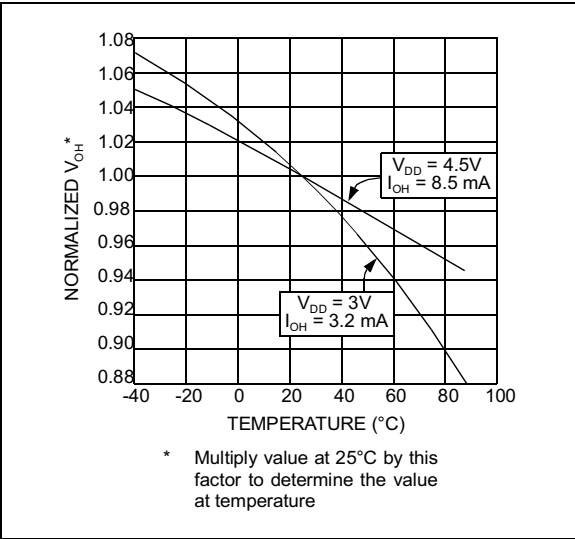


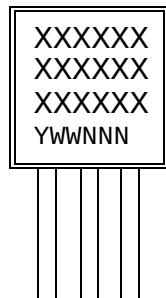
Figure 2-9: Normalized V_{OH} vs. Temperature

3.0 PACKAGING INFORMATION

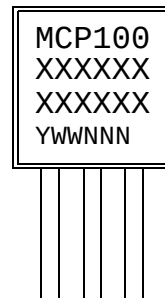
3.1 Package Marking Information

ILLUSTRATIONS NOT TO SCALE

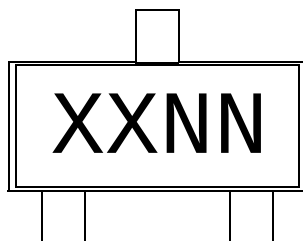
3-Lead Plastic Transistor Outline (TO-92)



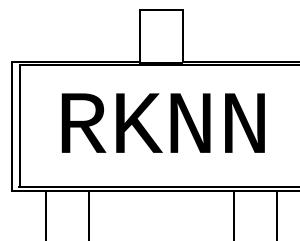
Example:



3-Lead Plastic Small Outline Transistor (SOT23)



Example:



SOT23 PARTS LABELING:

The table below identifies the first 2 characters (XX) in the 4-character field (XXNN) for marking of the 3-Lead SOT23 package.

Mark	Part Number	Mark	Part Number
QJ	MCP100T-270I/TT	RJ	MCP101T-270I/TT
QK	MCP100T-300I/TT	RK	MCP101T-300I/TT
QL	MCP100T-315I/TT	RL	MCP101T-315I/TT
QM	MCP100T-450I/TT	RM	MCP101T-450I/TT
QN	MCP100T-460I/TT	RN	MCP101T-460I/TT
QO	MCP100T-475I/TT	RO	MCP101T-475I/TT
QP	MCP100T-485I/TT	RP	MCP101T-485I/TT

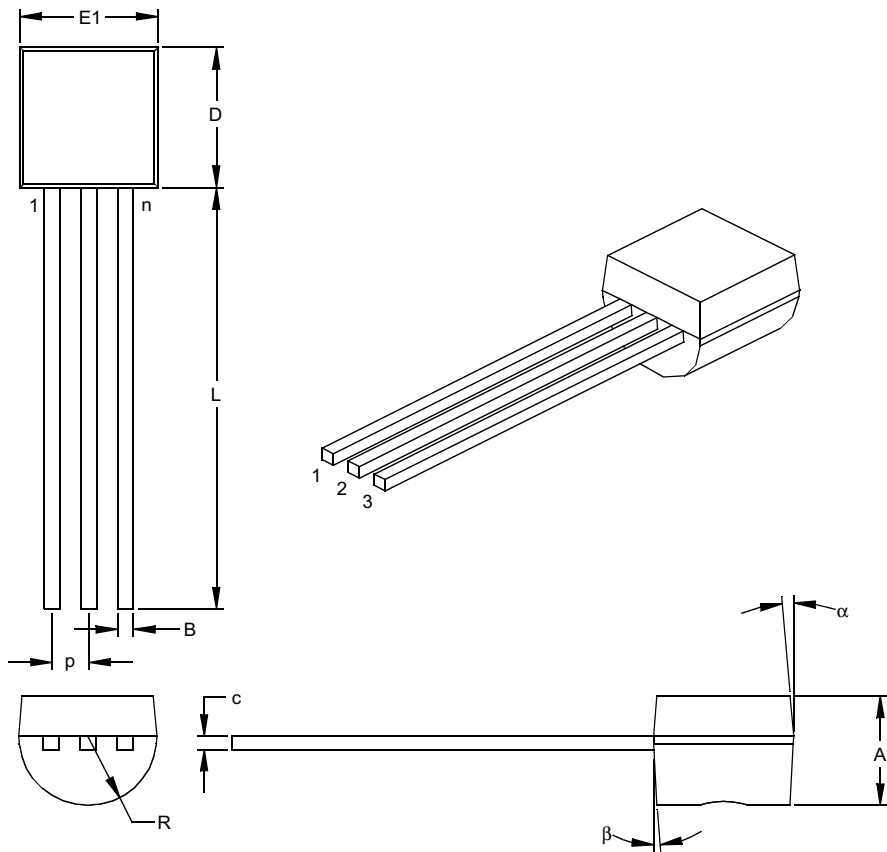
Legend:	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

* Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.

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3.2 Package Detail Information

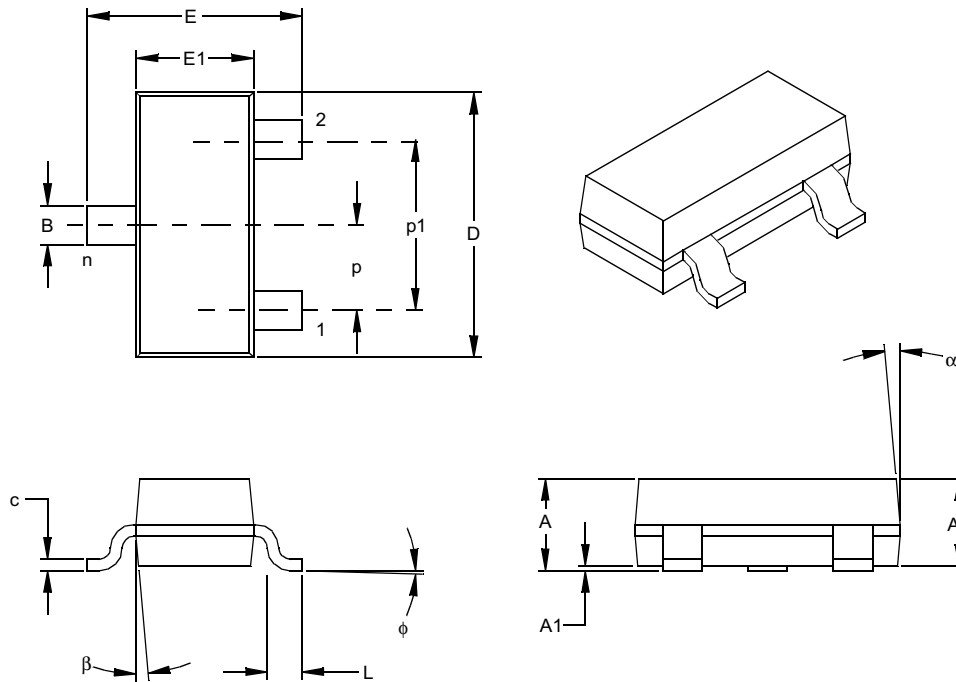
3-Lead Plastic Transistor Outline (TO) (TO-92)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.050			1.27	
Bottom to Package Flat	A	.130	.143	.155	3.30	3.62	3.94
Overall Width	E1	.175	.186	.195	4.45	4.71	4.95
Overall Length	D	.170	.183	.195	4.32	4.64	4.95
Molded Package Radius	R	.085	.090	.095	2.16	2.29	2.41
Tip to Seating Plane	L	.500	.555	.610	12.70	14.10	15.49
Lead Thickness	c	.014	.017	.020	0.36	0.43	0.51
Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Mold Draft Angle Top	α	4	5	6	4	5	6
Mold Draft Angle Bottom	β	2	3	4	2	3	4

*Controlling Parameter
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: TO-92
Drawing No. C04-101

3-Lead Plastic Small Outline Transistor (TT) (SOT23)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.038			0.96	
Outside lead pitch (basic)	p1		.076			1.92	
Overall Height	A	.035	.040	.044	0.89	1.01	1.12
Molded Package Thickness	A2	.035	.037	.040	0.88	0.95	1.02
Standoff §	A1	.000	.002	.004	0.01	0.06	0.10
Overall Width	E	.083	.093	.104	2.10	2.37	2.64
Molded Package Width	E1	.047	.051	.055	1.20	1.30	1.40
Overall Length	D	.110	.115	.120	2.80	2.92	3.04
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.007	0.09	0.14	0.18
Lead Width	B	.015	.017	.020	0.37	0.44	0.51
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: TO-236

Drawing No. C04-104

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To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	X	X	/XX
Device	RESET/ RESET V _{TRIP} Voltage	Bondout Option	Temperature Range	Package
Device:	MCP100: Supervisor circuit with active low $\overline{\text{RESET}}$ output			
	MCP100T: Supervisor circuit with active low $\overline{\text{RESET}}$ output (tape & reel)			
	MCP101: Supervisor circuit with active high $\overline{\text{RESET}}$ output			
	MCP101T: Supervisor circuit with active high $\overline{\text{RESET}}$ output (tape & reel)			
RESET/RESET V _{TRIP} Voltage:	270 = $2.55 \leq V_{\text{TRIP}} \leq 2.70$			
	300 = $2.85 \leq V_{\text{TRIP}} \leq 3.00$			
	315 = $3.00 \leq V_{\text{TRIP}} \leq 3.15$			
	450 = $4.25 \leq V_{\text{TRIP}} \leq 4.50$			
	460 = $4.35 \leq V_{\text{TRIP}} \leq 4.60$			
	475 = $4.50 \leq V_{\text{TRIP}} \leq 4.75$			
	485 = $4.60 \leq V_{\text{TRIP}} \leq 4.85$			
Bondout Option: (TO-92 Only)	D = D Bond Option (see bond option chart)			
	H = H Bond Option			
Temperature Range:	I = -40°C to +85°C (only offered in I)			
Package:	TO = TO-92 (3-lead) [offered in bags only]			
	TT = SOT-23 (3-lead) [offered in tape & reel only]			

Examples:

a) MCP100-270DI/TO = V_{TRIP} range of 2.55V - 2.70V, Bonding Option D, Industrial Temp., TO-92 package

b) MCP100T-450I/TT = V_{TRIP} range of 4.25V - 4.50V, Industrial Temp., SOT-23 package

c) MCP101-270HI/TO = V_{TRIP} range of 2.55V - 2.70V, Bonding Option H, Industrial Temp., TO-92 package

d) MCP101T-315I/TT = V_{TRIP} range of 3.00V - 3.15V, Industrial Temp., SOT-23 package

TO-92 with 'D' Bondout

TO-92 with 'H' Bondout

SOT-23-3

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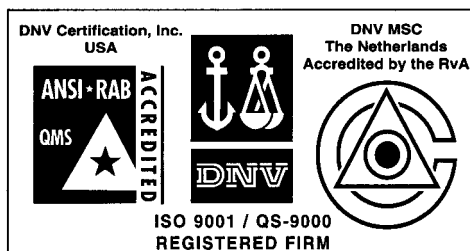
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